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OSMM&N File No. 245724US2X

Dept.: E/M

By: EHK/PAS/jyh

Serial No. 10/717,718

In the matter of the Application of: Yasutaka NISHIOKA, et al.

For: ELECTRONIC DEVICE MANUFACTURING METHOD

Due Date: N/A

The following has been received in the U.S. Patent Office on the date stamped hereon:

- Dep. Acct. Order Form
- Cover Letter
- Petition For Consideration Under 37 CFR 1.181(a)(3)
- Date-Stamped Filing Receipt dated November 21, 2003 (Copy)
- Information Disclosure Statement filed on November 21, 2003 (Copy)
- Form PTO-1449 filed on November 21, 2003 (Copy)



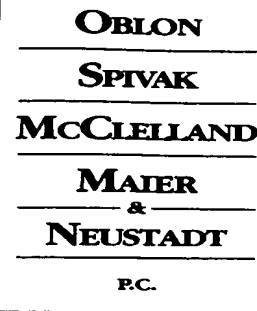
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CONFIDENTIAL



COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

DATE ALLOWED: October 20, 2004



ATTORNEYS AT LAW

Docket No.: 245724US2X

RE: Application Serial No.: 10/717,718
Inventor: Yasutaka NISHIOKA, et al.
Filing Date: November 21, 2003
For: ELECTRONIC DEVICE MANUFACTURING METHOD
Group: 3729
Examiner: Carl J. ARBES

SIR:

Attached hereto for filing are the following papers:

**PETITION FOR CONSIDERATION UNDER 37 CFR §1.181(a)(3)
DATE-STAMPED FILING RECEIPT DATED NOVEMBER 21, 2003 (COPY)
INFORMATION DISCLOSURE STATEMENT FILED ON NOVEMBER 21, 2003 (COPY)
FORM PTO 1449 FILED ON NOVEMBER 21, 2003 (COPY)**

Our credit card form in the amount of \$0.00 is attached covering any required fees. In the event any variance exists between the amount enclosed and the Patent Office charges for filing the above-noted documents, including any fees required under 37 CFR 1.136 for any necessary Extension of Time to make the filing of the attached documents timely, please charge or credit the difference to our Deposit Account No. 15-0030. Further, if these papers are not considered timely filed, then a petition is hereby made under 37 CFR 1.136 for the necessary extension of time.

Respectfully Submitted,

OBLON, SPIVAK, McCLELLAND,
MAIER & NEUSTADT, P.C.

Eckhard H. Kuesters
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(OSMMN 05/04)

Paul A. Sacher
Registration No. 43,418

COPY

DOCKET NO: 245724US2X



IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF :
YASUTAKA NISHIOKA, ET AL. : EXAMINER: CARL J. ARBES
SERIAL NO: 10/717,718 :
FILED: NOVEMBER 21, 2003 : GROUP ART UNIT: 3729
FOR: ELECTRONIC DEVICE :
MANUFACTURING METHOD :

PETITION FOR CONSIDERATION UNDER 37 CFR §1.181(a)(3) RE:
INFORMATION DISCLOSURE STATEMENT FILING(S)

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

This is a Petition pursuant to 37 CFR §1.181(a)(3) requesting that the Examiner be instructed by the Commissioner or his representative to notify Applicants of proper consideration of the information disclosure statement (IDS) that was filed on November 21, 2003.

STATEMENT OF FACTS

On November 21, 2003, Applicants filed the above-noted IDS under 37 CFR §§1.97 and 1.98, which filing is clearly documented by the attached copy of the associated date-stamped Mail Room receipt and copies of the IDS papers including the Form PTO 1449 and cited references (4). The PTO has not responded to this IDS filing by supplying Applicants with a copy of the Form PTO 1449 filed on November 21, 2003, that has been properly initialed by the Examiner.

COPY

POINT FOR REVIEW

The point for review is why Applicants have not been provided a copy of the above-noted Form PTO 1449 filed on November 21, 2003, properly initialed by the Examiner in compliance with the rules.

ACTION REQUESTED

In light of the above, it is respectfully requested that the Examiner be directed to provide Applicants a copy of the above-noted Form PTO 1449 filed on November 21, 2003, properly initialed by the Examiner in compliance with the rules.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND
MAIER & NEUSTADT, P.C.

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22850

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(OSMMN 06/04)

GJM/PAS/jyh

Eckhard H. Kuesters

Registration No. 28,870

Attorney of Record

Paul A. Sacher

Registration No. 43,418

CONFIDENTIAL



sm.
ms

OSMM&N File No. 245724US2X

Serial No. New Application

In the matter of the Application of: Yasutaka NISHIOKA, et al.

For: ELECTRONIC DEVICE MANUFACTURING METHOD

Dept.: PP/JF

By: MJS/als

Due Date: 1/21/04

The following has been received in the U.S. Patent Office on the date stamped hereon:

- 35 pp. Specification 20 Claims/Drawings 16 Sheets and
3 Pages Application Data Sheet
- Combined Declaration, Petition & Power of Attorney 4 Pages
- Utility Patent Application Transmittal
- Request for Priority
- Priority Doc 1
- Credit Card Form for \$810.00
- Dep. Acct. Order Form
- Fee Transmittal Form
- Assignment/PTO 1595 Pages: 3
- Information Disclosure Statement
- PTO-1449
- Cited References 4
- White Advance Serial Number Card



COPY

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Yasutaka NISHIOKA, et al.

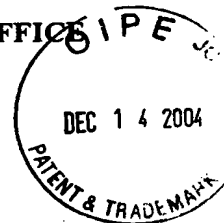
SERIAL NO: New Application

FILED: Herewith

FOR: ELECTRONIC DEVICE MANUFACTURING METHOD

GAU:

EXAMINER:



INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

Applicant(s) wish to disclose the following information.

REFERENCES

- ☒ The applicant(s) wish to make of record the references listed on the attached form PTO-1449. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.
- ☐ A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

RELATED CASES

- ☐ Attached is a list of applicant's pending application(s) or issued patent(s) which may be related to the present application. A copy of the patent(s), together with a copy of the claims and drawings of the pending application(s) is attached along with PTO 1449.
- ☐ A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

CERTIFICATION

- ☐ Each item of information contained in this information disclosure statement was first cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- ☐ No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

DEPOSIT ACCOUNT

- ☒ Please charge any additional fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit account number 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,
MAIER & NEUSTADT, P.C.

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COPY

Form PTO 1449
(Modified)U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE

ATTY DOCKET NO.

245724US2X

SERIAL NO.

New Application

LIST OF REFERENCES CITED BY APPLICANT

DEC 14 2004

APPLICANT

Yasutaka NISHIOKA, et al.

FILING DATE

Herewith

GROUP

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
	AL						
	AM						
	AN						

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION	
					YES	NO
	AO	2000-269326	9/29/00	Japan (with English Extract)		X
	AP					
	AQ					
	AR					
	AS					
	AT					
	AU					
	AV					

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)

	AW	S. M. JANG, et al., "INTEGRATION OF CU AND LOW-K MATERIAL FOR DUAL-DAMASCENE PROCESS", Semiconductor Technology, (ISTC 2001), Vol. I, Pages 485-493
	AX	K. HIGASHI, et al., "A MANUFACTURABLE COPPER/LOW-K SiOC/SiCN PROCESS TECHNOLOGY FOR 90NM-NODE HIGH PERFORMANCE eDRAM", Proceedings of the 2002 International Interconnect Technology Conference, Pages 15-17
	AY	M. FAYOLLE, et al., "INTEGRATION OF Cu/SiOC IN DUAL DAMASCENE INTERCONNECT FOR 0.1µm TECHNOLOGY USING A NEW SiC MATERIAL AS DIELECTRIC BARRIER", Proceedings of the 2002 International Interconnect Technology Conference, Pages 39-41
	AZ	

☐ Additional References sheet(s) attached

Examiner

Date Considered

*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

COPY